

ABSTRACT OF THE DISCLOSURE

A small memory card includes a first substrate, a heat sink, a second substrate, at least one upper memory chip, at least one bottom memory chip and a glue layer. The heat sink is arranged between the first substrate and second substrate, and contacted with the metal, which are filled within the plurality of through holes, which formed between the first substrate and second substrate. And each of the upper memory chips and bottom memory chips are mounted on the first substrate and the second substrate, so that the heat of the upper and bottom memory chips may be traveled to the heat sink via the metal, which is filled within the through hole, then the heat will be dispersed. Thus, the small memory card of present invention having high function of disperses heat to promote its durability and lifetime effectively, the manufacturing processes must be simplified and the manufacturing cost must decrease also.